

<b>Notice of References Cited</b>	Application/Control No. 10/683,575		Applicant(s)/Patent Under Reexamination OZIS ET AL.	
	Examiner Russell Frejd		Art Unit 2128	Page 1 of 1

#### U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,725,185	04-2004	Clement, Francois J. R.	703/14
*	B	US-6,895,344	05-2005	Ramaswamy, Sridhar	702/57
*	C	US-6,941,258	09-2005	Van Heijningen et al.	703/16
*	D	US-2001/0029601	10-2001	Kimura et al.	716/19
*	E	US-7,016,820	03-2006	Kimura et al.	703/2
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

#### FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

#### NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	BECER et al., M. Analysis of Noise Avoidance Techniques in DSM Interconnects Using a Complete Crosstalk Noise Model, Proceedings of the Conference on Design, Automation and Test in Europe, IEEE Computer Society, March 2002, pp. 1-8.
	V	COSTA et al., J.P. Precorrected-DCT Techniques for Modeling and Simulation of Substrate Coupling in Mixed-Signal IC", Proceedings of the 1998 IEEE International Symposium on Circuits and Systems, Vol. 6, May-June 1998, pp. 358-62.
	W	KOUKAB et al., A. HspeedEx: A High Speed Extractor for Substrate Noise Analysis in Complex Mixed-Signal SOC, IEEE, Proceedings of the 39th Design Automation Conference, June 2002, pp. 767-70.
	X	CHOU et al., M. Multilevel Integral Equation Methods for the Extraction of Substrate Coupling Parameters in Mixed-Signal IC's, IEEE, Design Automation Conference, June 1998, pp. 20-5.

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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